# isola

# TerraGreen® 400G2

Halogen-free, Extremely Low Loss Material Tg 200°C Td 380°C Dk 3.10 Df 0.0015

# IPC-4101 /134 UL - File Number E41625

# TerraGreen® 400G2 laminate materials are our most advanced ultra-high speed, halogen free extremely-low loss design solution.

#### **PRODUCT FEATURES**

Industry Recognition

- UL File Number: E41625
- RoHS Compliant

#### Performance Attributes

- CAF resistant
- Low moisture absorption
- Halogen free
- 6x 260°C reflow capable
- 6x 288°C solder float capable

Processing Advantages

- FR-4 process compatible
- Excellent Fill and Flow
- Multiple lamination cycles
- HDI technology compatible

## **PRODUCT AVAILABILITY**

Standard Material Offering: Laminate • 2 to 10 mil (0.05 to 0.25 mm)

Copper Foil Type

• HVLP3 (VLP1)  $\leq$ 1.1 micron Rz JIS Copper Weight

- ½, 1 and 2 oz (18, 35 and 70 μm) available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging
- Glass Fabric Availability
  - Very Low Dk glass
  - Square weave glass
  - Mechanically spread glass

### **ORDERING INFORMATION:**

Contact your local sales representative or contact <u>info@isola-group.com</u> for further information.

TerraGreen® 400G2 is our Halogen Free material solution for next generation 5G infrastructure, data center systems, high end computing, wired & wireless communications and AI applications. Our novel resin system, ultra smooth HVLP3(VLP1) copper foil and 2nd generation Ultra Low Dk glass has been engineered for very high data rates of >100 Gb/s with excellent cost for loss performance.

The TerraGreen® 400G2 resin system has proven superior CAF performance on tight pitch testing. CAF performance is enhanced by the resin systems excellent interlaminar and bond line adhesion strength.

TerraGreen® 400G2 is lead free compatible and sequential lamination capable and can be processed utilizing standard PCB equipment and processing steps. TerraGreen® 400G2 meets UL94 V-0.

# **PRODUCT ATTRIBUTES**



# Isola Group

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# **Typical Values Table**

| Property   |  |                            | Units                 | Test Method              |
|--|--|----------------------------|-----------------------|--------------------------|
|  |  | Typical Value              | Metric (English)      | IPC-TM-650 (or as noted) |
| Glass Transition Temperature (Tg) by DSC               |  | 200                        | °C                    | 2.4.25C                  |
| Glass Transition Temperature (Tg) by DMA               |  | 215                        | °C                    | 2.4.24.4                 |
| Glass Transition Temperature (Tg) by TMA               |  | 180                        | °C                    | 2.4.24C                  |
| Decomposition Temperature (Td) by TGA @ 5% weight loss |  | >380                       | °C                    | 2.4.24.6                 |
| Time to Delaminate by TMA<br>(Copper removed)          | A. T260<br>B. T288   | 60+                        | Minutes               | 2.4.24.1                 |
| Z-Axis CTE   | A. Pre-Tg<br>B. Post-Tg<br>C. 50 to 260°C, (Total Expansion)   | 37<br>170<br>1.8           | ppm/°C<br>ppm/°C<br>% | 2.4.24C                  |
| X/Y-Axis CTE   |  | 12/13                      | ppm/°C                | 2.4.24C                  |
| Thermal Conductivity                                   |  | 0.54                       | W/m·K                 | ASTM E1952               |
| Thermal Stress 10 sec @ 288ºC<br>(550.4ºF)             | A. Unetched<br>B. Etched   | Pass                       | Pass Visual           | 2.4.13.1                 |
| Dk, Permittivity                                       | A. @ 10 GHz<br>B. @ 20 GHz   | 3.10<br>3.07               | -                     | 2.5.5.5                  |
| Df, Loss Tangent                                       | A. @ 10 GHz<br>B. @ 20 GHz   | 0.0015                     | _                     | 2.5.5.5                  |
| Volume Resistivity                                     | C-96/35/90   | 2.0x10 <sup>8</sup>        | MΩ-cm                 | 2.5.17.1                 |
| Surface Resistivity                                    |  | 2.0x10 <sup>7</sup>        | MΩ                    | 2.5.17.1                 |
| Dielectric Breakdown                                   |  | 70                         | kV                    | 2.5.6B                   |
| Arc Resistance   |  | 180                        | Seconds               | 2.5.1B                   |
| Electric Strength (Laminate & laminated prepreg)       |  | 67 (1700)                  | kV/mm (V/mil)         | 2.5.6.2A                 |
| Comparative Tracking Index (CTI)                       |  | 2 (250-499)                | Class (Volts)         | UL 746A<br>ASTM D3638    |
| Peel Strength  | <ul><li>A. Low profile and very low profile</li><li>copper foil</li><li>B. Low profile and very low profile</li><li>copper foil After thermal stress</li></ul> | 0.7 (4.1)                  | N/mm (lb/inch)        | 2.4.8C<br>2.4.8.2A       |
| Flexural Strength                                      | A. Length direction<br>B. Cross direction  | 393 (57)<br>338 (49)       | MPa (kpsi)            | 2.4.4B                   |
| Tensile Strength                                       | A. Length direction<br>B. Cross direction  | 220 (32)<br>193 (28)       | MPa (kpsi)            | ASTM D3039               |
| Young's Modulus  | A. Length direction<br>B. Cross direction  | 14.5 (2100)<br>13.0 (1900) | GPa(kpsi)             | ASTM D790-15e2           |
| Flexural Modulus                                       | A. Lengthwise<br>B. Crosswise  | 12.1 (1750)<br>11.7 (1700) | GPa (kpsi)            | ASTM D790-15e2           |
| Poisson's Ratio  | A. Length direction<br>B. Cross direction  | 0.17<br>0.22               | _                     | ASTM D3039               |
| Moisture Absorption                                    |  | <0.1                       | %                     | 2.6.2.1A                 |
| Flammability (Laminate & laminated prepreg)            |  | V-0                        | Rating                | UL 94                    |
| Relative Thermal Index (RTI)                           |  | 140                        | °C                    | UL 746                   |

## NOTES

## Notes:

All data is preliminary and subject to change \* Data was developed using 55% RC rigid laminate

Revisions:

- A: Preliminary Release 1/23
- B: Corrected units for Youngs Modulus from MPa to GPa 1/24
- C: Corrected laminate thickness offering from maximum 18 mils to 10 mils, updated copper foil offering 3/24

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